

KM-23LSGD-F SUPER BRIGHT GREEN

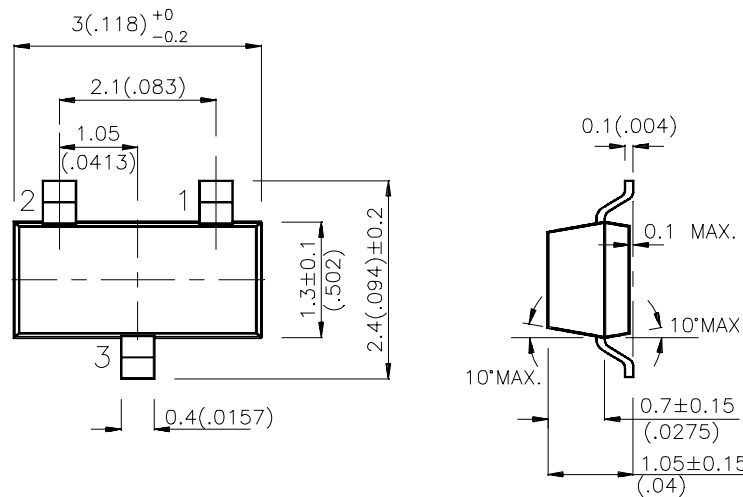
### Features

- SOT-23 PACKAGE SURFACE MOUNT LED LAMP.
- LOW POWER CONSUMPTION.
- LONG LIFE - SOLID STATE RELIABILITY.
- PACKAGE: 2000PCS / REEL.
- LOW CURRENT IF=2mA OPERATING.

### Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

### Package Dimensions



- 1 ANODE  
2 N.C.  
3 CATHODE

#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 2mA		Viewing Angle
			Min.	Typ.	2θ1/2
KM-23LSGD-F	SUPER BRIGHT GREEN (GaP)	GREEN DIFFUSED	0.1	0.25	140°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

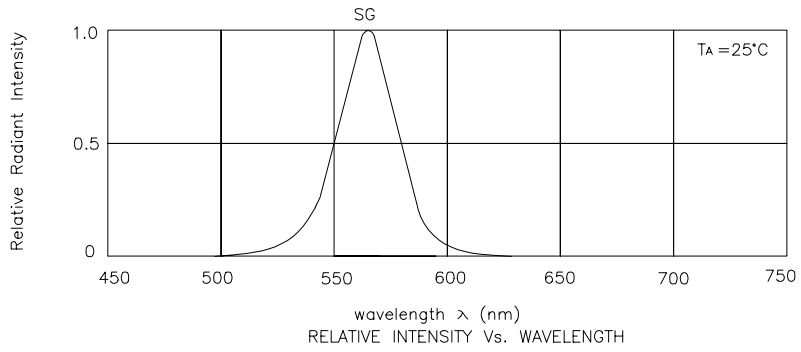
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Super Bright Green	565		nm	I <sub>F</sub> =20mA
λ <sub>D</sub>	Dominate Wavelength	Super Bright Green	568		nm	I <sub>F</sub> =20mA
Δλ <sub>1/2</sub>	Spectral Line Half-width	Super Bright Green	30		nm	I <sub>F</sub> =20mA
C	Capacitance	Super Bright Green	15		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub>	Forward Voltage	Super Bright Green	2.2	2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Super Bright Green		10	uA	V <sub>R</sub> = 5V

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

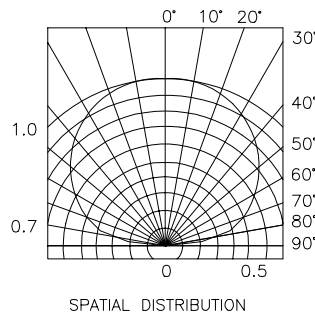
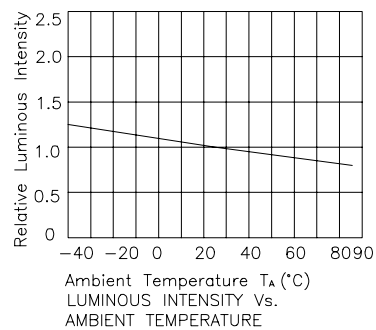
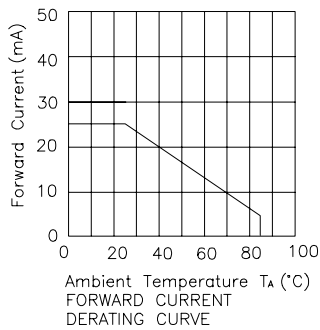
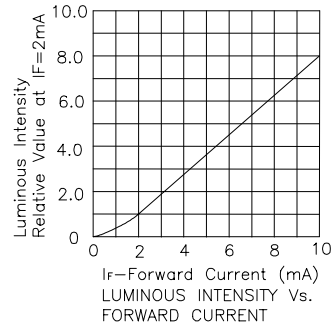
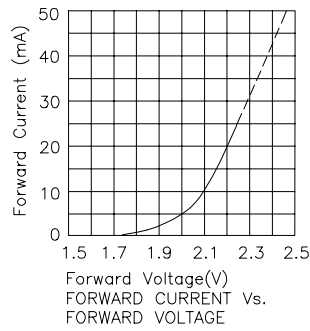
Parameter	Super Bright Green	Units
Power dissipation	105	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

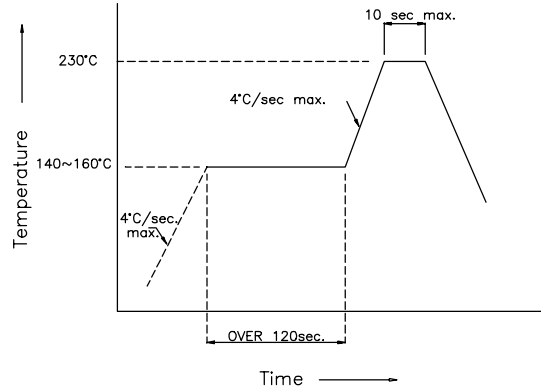


## Super Bright Green KM-23LSGD-F

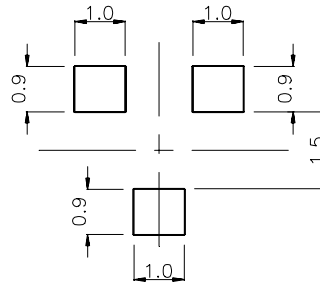


## KM-23LSGD-F SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



### Recommended Soldering Pattern (Units : mm)



### Tape Specifications (Units : mm)

